



(51) International Patent Classification:

H05K 1/11 (2006.01) B41J 2/175 (2006.01)
B41J 2/14 (2006.01) H05K 1/18 (2006.01)

(21) International Application Number:

PCT/US2023/026869

(22) International Filing Date:

03 July 2023 (03.07.2023)

(25) Filing Language:

English

(26) Publication Language:

English

(71) Applicant: **HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P.** [US/US]; 10300 Energy Drive, Spring, Texas 77389 (US).

(72) Inventors: **QUINN, Max**; 1070 NE Circle Blvd., Corvallis, 97330-4241 (US). **BAHNSEN, Kyle**; 1115 SE 164th Avenue, Suite 210, Columbia Tech Center, Columbia Center, Suite 210, Vancouver, Washington 98683 (US). **SCHWEITZER, Paul**; 1070 NE Circle Blvd., Corvallis, Oregon 97330-4241 (US). **CUMBIE, Michael W.**; 1070 NE Circle Blvd., Corvallis, Oregon 97330-4241 (US). **GARDNER, James**; 1070 NE Circle Blvd., Corvallis, Oregon 97330-4241 (US). **MCCOURT, Zachary**; Persiaran Cassia

Selatan 2, Taman Perindustiran Batu Kawan, Pulau Pinang, 14100 (MY). **STUMBO, Samuel**; 1070 NE Circle Blvd., Corvallis, Oregon 97330-4241 (US).

(74) Agent: **HUNTER, Paul S.** et al.; 3000 K Street N.W., Suite 600, Washington, District of Columbia 20007 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,

(54) Title: INTERCONNECT CIRCUIT FOR PRINT COMPONENT

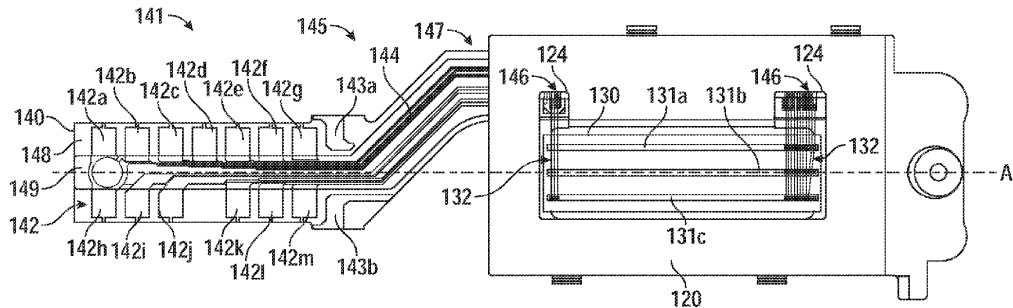


FIG. 4

(57) Abstract: An interconnect circuit may include a first portion including an electrical interconnect pad array to connect to the host controller, the electrical interconnect pad array including a first electrical interconnect pad on a first lateral side of the first portion, and a second electrical interconnect pad on a second lateral side of the first portion, a second portion separate from the first portion, including a contact pad array to connect to the integrated circuit, the contact pad array on the first surface the second portion including a first contact pad to connect to a fluid ejection device, a second contact pad to connect to the fluid ejection device, a first trace connecting the first electrical interconnect pad and first contact pad, and a second trace connecting the second electrical interconnect pad and second contact pad, where the first trace is configured to conduct a higher voltage than the second trace.

[Continued on next page]

LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*